

REMARKS

This application has been reviewed in light of the Office Action dated March 14, 2006. A replacement paragraph and corrected Figure 2 are hereby presented to place the application in condition for allowance.

Favorable review is respectfully requested.

The Specification:

A replacement paragraph for paragraph [0026] has been provided to insert reference numeral 13 after -- an upper, heavily doped, polysilicon layer --.

Drawings:

A replacement Figure 2 has been provided to include reference numeral 21 which represents the thickness of element 13.

Summary:

In view of all the preceding amendments and remarks, it is respectfully requested that any objections or rejections to this application be reconsidered and withdrawn. Further action with respect to the present application is earnestly solicited. If the Examiner finds this application is deficient in any respect, the Examiner is invited to contact the undersigned at the Examiner's earliest possible convenience.

For the foregoing reasons, allowance of the claims is respectfully solicited.

Respectfully submitted,
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